



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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Product Description

Laird Tflex HD400 is a 4.0 W/mK gap filling material in our high deflection line of products. Tflex HD400 is an excellent choice when wide manufacturing tolerances occur. These variable gaps can be filled with Tflex HD400 while generating minimal board and component stress. Laird's unique manufacturing capabilities, filler and resin knowledge result in this advanced product designed with customer applications in mind.

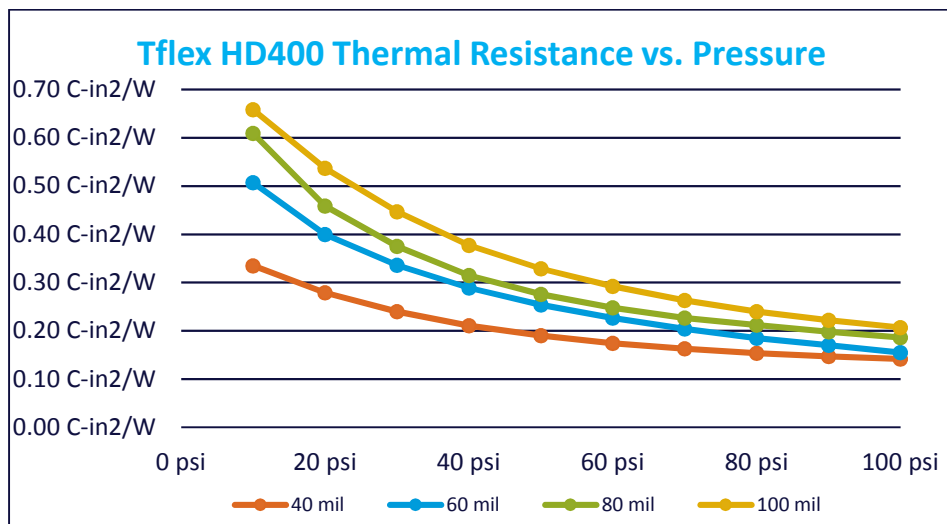
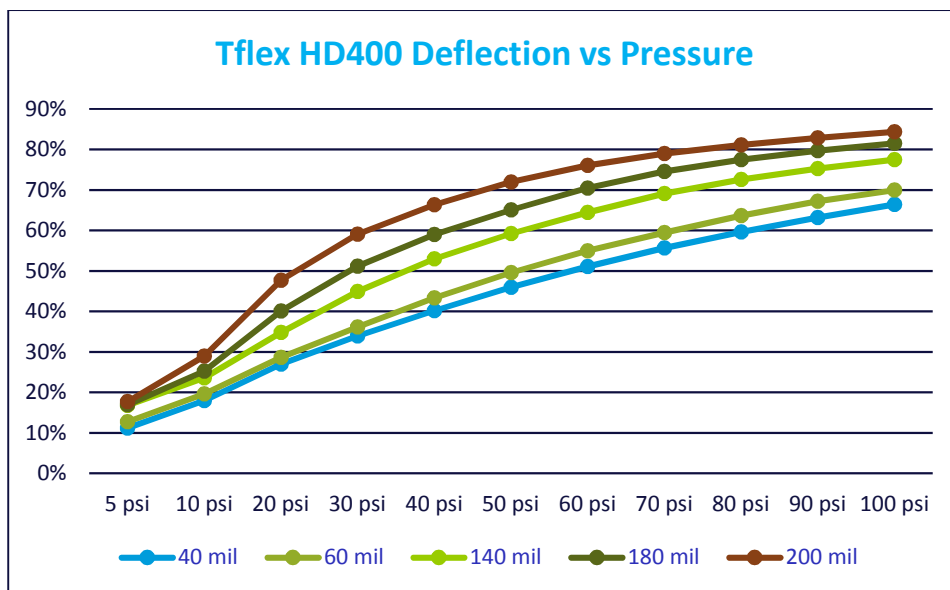
Tflex HD400 is provided in thickness from 0.5mm (.020") up to 5mm (0.200") in 0.25mm (.020") increments as standard. In addition, Laird can provide Tflex HD400 in multiple converted formats through approved converters and distribution networks.

FEATURES AND BENEFITS

- 4.0 W/mK thermal conductivity
- Low pressure versus deflection
- Excellent surface wetting for low contact resistance
- Minimizes board and component stress
- Large tolerance applications
- RoHS and REACH compliant

SPECIFICATIONS

TYPICAL PROPERTIES	VALUE	TEST METHOD
Construction & Composition	Ceramic filled silicone sheet	N/A
Color	Blue	Visual
Thickness Range	0.5 mm (0.020") - 5.0mm (0.200")	N/A
Thermal Conductivity (W/mK)	4.0	ASTM D5470
Density (g/cc)	3.0	Helium Pycnometer
Hardness (Shore 00)	44	ASTM D2240
Outgassing TML (weight %)	0.22	ASTM E595
Outgassing CVCM (weight %)	0.04	ASTM E595
Temperature Range	-40°C to 200°C	Laird Test Method
Rth@ 40 mils, 10 psi	0.36°C-in ² /W	ASTM D5470 (Modified)
Dielectric Constant @ 1 MHz	10.7	ASTM D150
UL Flammability Rating	V-0	UL 94
Volume Resistivity	2.8 x 10 ¹⁴	ASTM D257



AVAILABILITY

STANDARD THICKNESSES

- 0.5 mm (0.020") to 5.0mm (0.200") thick material available in 0.25mm (0.010") increments
- Available in standard sheet sizes of 18" x 18" and 9" x 9" or custom die cut parts

OPTIONS

- DC1 – eliminate tack from one side

PART NUMBER SYSTEM

Tflex™ indicates Laird elastomeric thermal gap filler product line. HD4xxx indicates Tflex HD400 product line with thickness in mils (0.001")

EXAMPLES:

- Tflex™ HD440 = 0.040" thick Tflex™ HD400 material
- Tflex™ HD4100DC1 = 0.10" thick Tflex™ HD400 material with DC1 option

A17434-00 Tflex HD400 DS 070717